

SCHOTTKY RECTIFIER SMA

# SS32 thru SS320 SMA

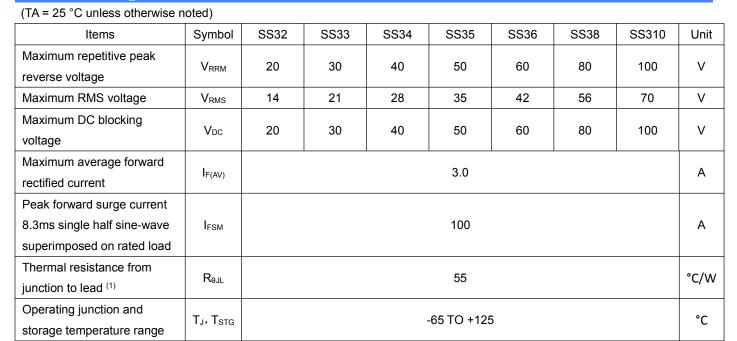
#### FEATURES

- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250 °C/10 seconds at terminals
- The plastic package carries Underwriters Laboratory
  Flammability Classification 94V-0

### Mechanical Date

- Case: JEDEC DO-214AC molded plastic
- Terminals: leads solderable per MIL-STD-750, Method 2026
- Mounting Position: Any
- Polarity: Color band denotes cathode end
- Weight: 0.005 ounce, 0.138 grams

## Maximum Ratings & Thermal Characteristics



T<sub>j max.</sub>

Note 1: Mounted on P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.



125 °C

### SMA (DO-214AC)

Major Ratings and Characteristics						
I <sub>F(AV)</sub>	3.0A					
V <sub>RRM</sub>	20 V to 100 V					
I <sub>FSM</sub>	100A					
VF	0.55V, 0.70V, 0.85V					



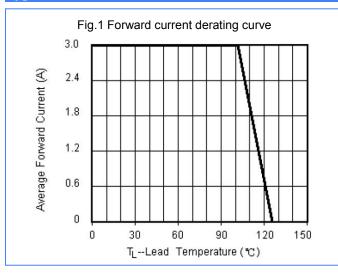
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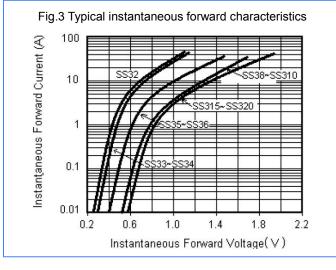
# Electrical Characteristics (TA = 25 °C unless otherwise noted)

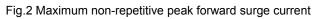
Items	Test conditions		Symbol	SS32~SS34	SS35~SS36	SS38~SS310	UNIT
Instantaneous forward voltage	IF=3.0A <sup>(2)</sup>		VF	0.55	0.70	0.85	V
Boveree ourrent	$\lambda = \lambda$	<b>T</b> j <b>=25</b> ℃	I <sub>R</sub>	0.5			~^^
Reverse current	V <sub>R</sub> =V <sub>DC</sub>	Tj <b>=100</b> ℃		20	10		mA
Typical junction capacitance	4.0 V ,1MHz		Cj	500	300		pf

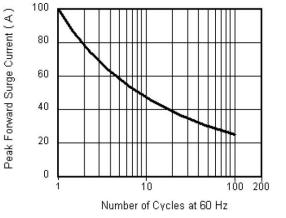
Note 2: Pulse test:300µs pulse width,1% duty cycle.

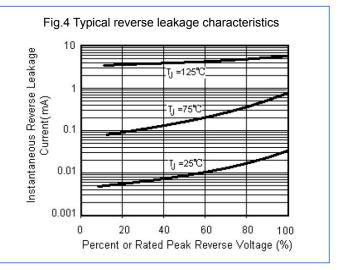
### **Typical Characteristics**





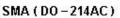


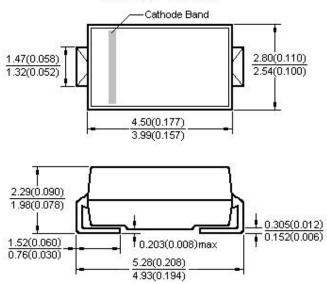






# Package Outline(SMA DO-214AC)





Dimensions in millimeters and (inches)

## Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.